

[Title of Invention] DICING SHEET, METHOD FOR PRODUCING DICING SHEET, AND METHOD FOR PRODUCING MOLD CHIPS

[Name of Document] Abstract

A dicing sheet comprising a base film and a pressure  
5 sensitive adhesive layer laminated on at least one surface of  
the base film, the pressure sensitive adhesive layer having a  
storage elastic modulus at 23°C of 50 kPa or more and 80 kPa  
or less before irradiation with energy rays and 5.0 MPa or more  
and 120 MPa or less after irradiation with energy rays, the  
10 pressure sensitive adhesive layer having a thickness of less  
than 20  $\mu\text{m}$ , the pressure sensitive adhesive layer having a  
surface of which an energy amount before irradiation with energy  
rays is 0.10 mJ/5 mm $\phi$  or more and 0.8 mJ/5 mm $\phi$  or less, the energy  
amount being measured using probe tack under a condition in  
15 which a peeling speed is changed to 1 mm/minute in a method as  
described in JIS Z0237:1991. The dicing sheet is less likely  
to cause troubles in the dicing step and problems regarding the  
printed character visibility in mold chips. The dicing sheet  
can be used thereby to produce high-quality mold chips excellent  
20 in the visibility of printed characters at low cost.